

Application Serial No. 10/618,955
Reply to Office Action of May 23, 2005

PATENT
Docket: CU-3290

Amendments To The Claims

The listing of claims presented below will replace all prior versions, and listings, of claims in the application.

Listing of claims:

1. (previously presented) A test vehicle ball grid array package comprising:
 - a PCB having bonding fingers;
 - a single semiconductor chip having a plurality of bonding pads adhered on the PCB;
 - an adhesive material being coated on an edge of the PCB;
 - a one or more sealing posts being adhered on the adhesive material,
 - wherein each sealing post comprises a vertical wall and an
extrusion is formed at connected to a upper end of the sealing post
vertical wall, and
 - further wherein the one or more sealing posts enclose the
lateral sides of the single semiconductor chip on the PCB such that
the extrusions connected to the one or more vertical walls are inside
the enclosure;
 - ~~a semiconductor testing chip having a plurality of bonding pads adhered on the PCB;~~
 - a plurality of metal wires separately connecting bonding pads of the PCB to the bonding fingers of the PCB;
 - a sealing cap adhered to the one or more extrusions connect to the vertical

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wall of the ~~on a~~ sealing post for sealing the single semiconductor chip from the top,

~~wherein the sealing cap is adhered on the extrusion of the sealing post~~; and

a plurality of solder balls adhered to a lower side of the PCB.

2. (original) A test vehicle ball grid array package according to claim 1, wherein each of the sealing post and the sealing cap is made from non-conductive material.
- 3-4. (cancelled)
5. (original) A test vehicle ball grid array package according to claim 4, wherein the sealing cap is adhered on the extrusion of the sealing post by a low temperature thermoplastic tape or a material similar to low temperature thermoplastic tape.
6. (original) A test vehicle ball grid array package according to claim 1, wherein the semiconductor chip is a center pad-type chip or an edge pad-type chip.